



Product Change Notification

Change Notification #: 115346 - 00
Change Title: Intel® Server Chassis H2312XXKR2
and H2216XXKR2,
PCN 115346-00,
Transport Media,
Packing Material Change

Date of Publication: March 15, 2017

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: * April 10, 2017

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is changing the internal packaging material on the Intel® Server Chassis H2312XXKR2 and H2216XXKR2 from card box to foam for better content protection. Please refer to the pictures below for the details of the change.

Please refer to the Products Affected table below for a summary of TA changes.



Figure 1. Before change (with cardboard)



Figure 2. After change (with foam)

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2312XXKR2	933689	H20865-009	H20865-010
H2216XXKR2	933688	H20866-009	H20866-010

PCN Revision History:

Date of Revision:
March 15, 2017

Revision Number:
00

Reason:
Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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